

# HFM101-MH THRU HFM107-MH

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# HFM101-MH THRU HFM107-MH

## 1.0A Surface Mount High Efficiency Rectifiers 50V-1000V

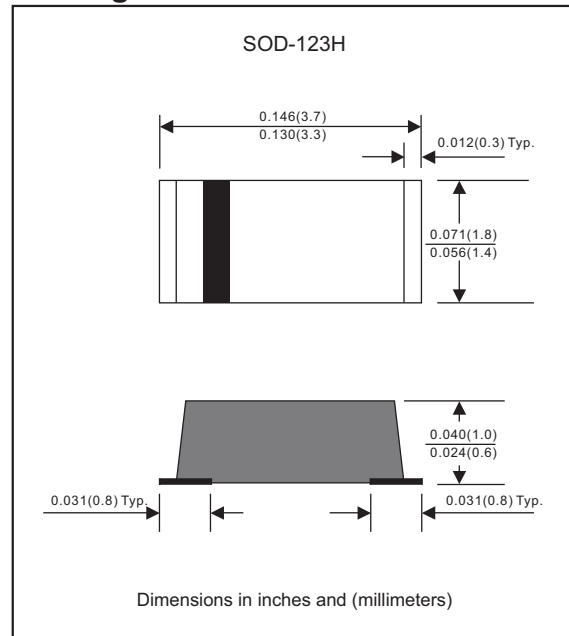
### Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance
- Low profile surface mounted application in order to optimize board space
- Tiny plastic SMD package
- High current capability
- Ultrafast recovery time for high efficiency
- High surge current capability
- Glass passivated chip junction
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicates Halogen free parts, ex. HFM101-MH-H

### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123H
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.011 gram

### Package outline



### Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	HFM101-MH	HFM102-MH	HFM103-MH	HFM104-MH	HFM105-MH	HFM106-MH	HFM107-MH	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum continuous reverse voltage	$V_R$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_o$	1.0							A
Non-repetitive peak forward surge current 8.3ms single half sine-wave	$I_{FSM}$	25							A
Typical junction capacitance (Note 1)	$C_J$	20							pF
Operating junction temperature range	$T_J$	-55 to +150							$^{\circ}\text{C}$
Storage temperature range	$T_{STG}$	-65 to +175							$^{\circ}\text{C}$

### Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	HFM101-MH	HFM102-MH	HFM103-MH	HFM104-MH	HFM105-MH	HFM106-MH	HFM107-MH	UNIT	
Maximum instantaneous forward voltage at $I_F=1.0\text{A}$	$V_F$	1.00			1.30	1.70			V	
Maximum reverse leakage current $T_J=25^{\circ}\text{C}$ at rated $V_R$ $T_J=125^{\circ}\text{C}$	$I_R$	5.0					150			$\mu\text{A}$ $\mu\text{A}$
Maximum reverse recovery time (Note 2)	$t_{rr}$	50				75				ns

### Thermal characteristics

PARAMETER	SYMBOLS	HFM101-MH	HFM102-MH	HFM103-MH	HFM104-MH	HFM105-MH	HFM106-MH	HFM107-MH	UNIT
Typical thermal resistance junction to ambient (Note 3)	$R_{\theta JA}$	67							$^{\circ}\text{C}/\text{W}$
Typical thermal resistance junction to case (Note 3)	$R_{\theta JC}$	52							$^{\circ}\text{C}/\text{W}$

Notes 1: Measured at 1 MHz and applied reverse voltage of 4.0 VDC

2: Measured with  $I_F = 0.5\text{A}$ ,  $I_R = 1\text{A}$ ,  $I_{rr} = 0.25\text{A}$

3: Mounted on FR-4 PCB Copper, minimum recommended pad layout

# Rating and characteristic curves (HFM101-MH THRU HFM107-MH)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

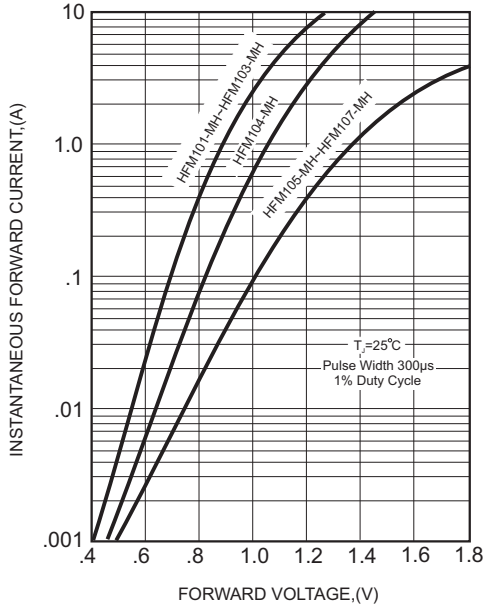


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

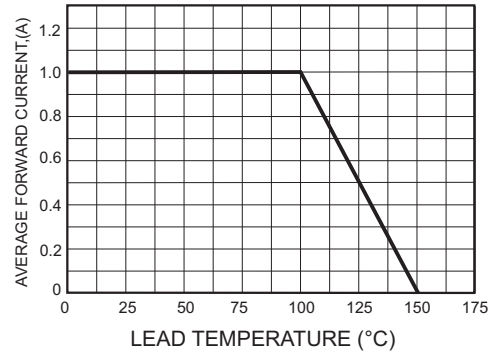


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

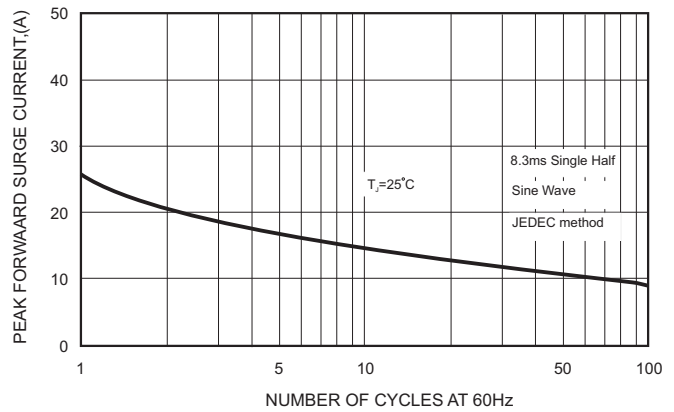
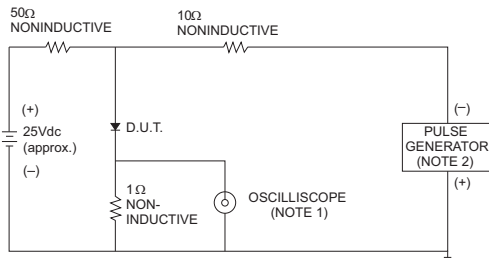


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



- NOTES: 1. Rise Time = 7ns max., Input Impedance = 1 megohm, 22pF.  
2. Rise Time = 10ns max., Source Impedance = 50 ohms.

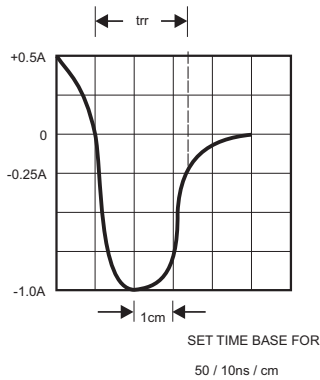
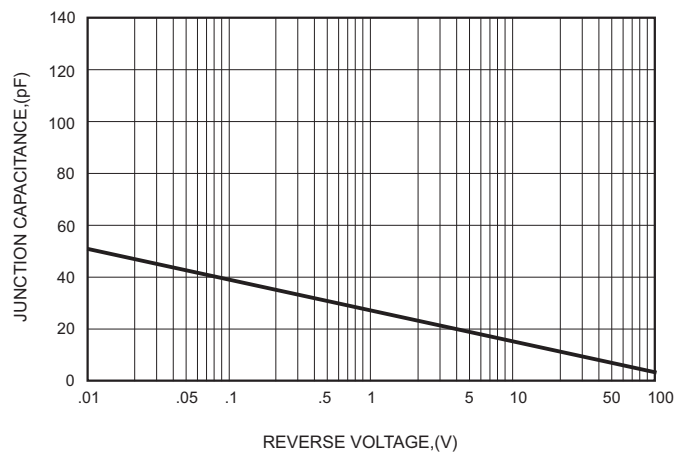




FIG.5-TYPICAL JUNCTION CAPACITANCE



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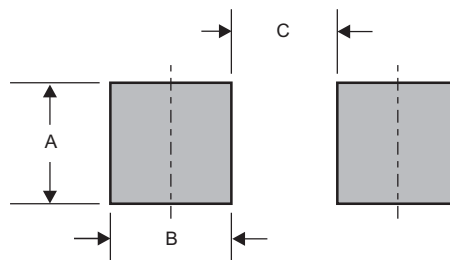
## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
HFM101-MH	H1
HFM102-MH	H2
HFM103-MH	H3
HFM104-MH	H4
HFM105-MH	H5
HFM106-MH	H6
HFM107-MH	H7

## Suggested solder pad layout

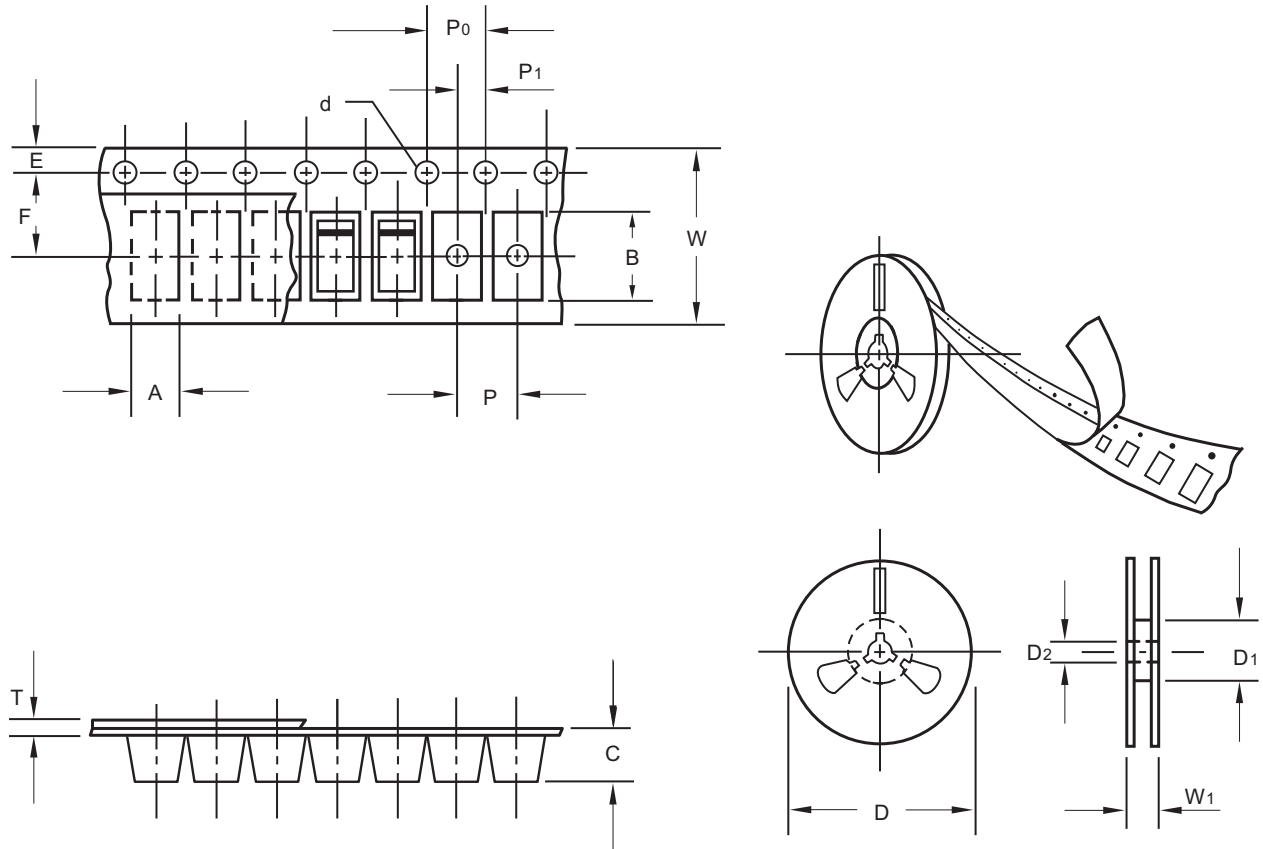


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123H	0.071 (1.80)	0.051 (1.30)	0.067 (1.70)

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## Packing information



unit:mm

Item	Symbol	Tolerance	SOD-123H
Carrier width	A	0.1	2.00
Carrier length	B	0.1	3.85
Carrier depth	C	0.1	1.10
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

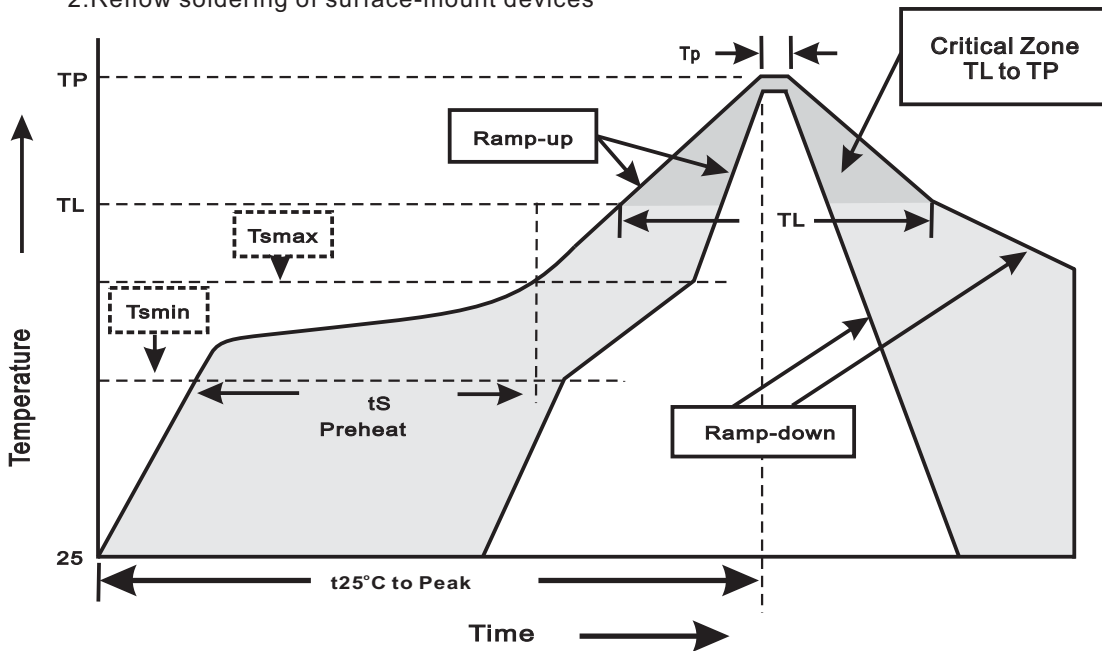
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## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123H	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	9.0

## Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



### 3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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## High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec.	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$ , $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	15P <sub>SIG</sub> at $T_A=121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^\circ\text{C}$ , RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031